In the Claims:

Please amend the claims as follows:

1. (currently amended) A method for manufacturing a power capacitor comprising at least one capacitor element ~~(1)~~, wherein the capacitor element ~~(1)~~ comprises a roll of alternate dielectric films ~~(4)~~ and electrode films ~~(2, 3)~~, wherein the roll has first and second end surfaces ~~(5, 6)~~, facing away from each other, in which said electrode films ~~(2, 3)~~ are connectably exposed, ~~characterized in that~~ the method comprising:

preheating a solder tip ~~(21) is preheated~~ in a pot ~~(20)~~ with a preheated solder, ~~that~~

coating the solder tip ~~is then coated~~ with solder, whereupon at least one of the end surfaces ~~(5, 6)~~ of the capacitor element is coated with at least one solder by bringing the solder tip ~~(21)~~ into contact with said end surface ~~(5, 6)~~, ~~that~~

bringing the contact ~~is brought~~ to cease, and ~~that~~

fixing at least one lead ~~(7, 9) is fixed~~ by soldering to said end surface ~~(5, 6)~~.

2. (currently amended) ~~A~~ The method according to claim 1, ~~characterized in that~~ wherein the capacitor element ~~(1)~~ is wound from the electrode films, comprising a first ~~aluminium~~ aluminum foil ~~(2)~~ and a second aluminum foil ~~(3)~~, with at least one intermediate dielectric film ~~(4)~~ of a polymer material, wherein the first ~~aluminium~~ aluminum foil ~~(2)~~ at the first end surface ~~(5)~~ of the capacitor element is arranged so as to project outside the edge of the polymer film ~~(4)~~, whereas at the same first end surface of the edge of the capacitor element the edge of the second ~~aluminium~~ aluminum foil ~~(3)~~ is arranged with its edge inside the edge of the

polymer film ~~(4)~~ so that the end ~~(5)~~ of the capacitor element exhibits the shape of a roll of the first ~~aluminium~~ aluminum foil ~~(2)~~ only and the second ~~aluminium~~ aluminum foil ~~(3)~~ is arranged so that the second end ~~(6)~~ of the capacitor element in a corresponding way exhibits the shape of a roll of the second ~~aluminium~~ aluminum foil ~~(3)~~ only, that wherein the solder tip comprises an active tip ~~(26)~~ which is coated with the solder, and ~~that~~ wherein the solder tip ~~(21)~~, after having been brought into contact with the end surface ~~(5, 6)~~ of the capacitor element, is moved along the end surface ~~(5, 6)~~ of the capacitor element.

3. (currently amended) ~~A~~ The method according to claim 2, ~~characterized in that~~ wherein the movement is carried out in one sequence comprising a starting point ~~(P1)~~, two turning points ~~(P2, P3)~~ between which the solder tip ~~(21)~~ is moved in one or more cycles, and one end point ~~(P4)~~ from which the solder tip ~~(21)~~ is removed from the end surface ~~(5, 6)~~ of the capacitor element, whereby the first or the second turning point ~~(P2, P3)~~ may be the same as the starting point ~~(P1)~~ or the end point ~~(P4)~~.

4. (currently amended) ~~A~~ The method according to ~~any of claim 2 or 3, characterized in that~~ claim 2, wherein the speed of movement of the solder tip along the end ~~(5, 6)~~ of the capacitor element is between 0 m/s and 0.1 m/s.

5. (currently amended) ~~A~~ The method according to ~~any of the preceding claims, characterized in that~~ claim 1, wherein the solder tip ~~(21)~~ when first being brought into contact with the end ~~(5, 6)~~ of the capacitor element presses down the end surface ~~(5, 6)~~ of the capacitor element.

6. (currently amended) ~~A~~ The method according to claim 5, ~~characterized in that~~ wherein the solder tip ~~(21)~~ is pressed down to a depth of between 0 and 6 mm in the end surface ~~(5, 6)~~ of the capacitor element.

7. (currently amended) ~~A~~ The method according to claim 6, ~~characterized in that~~ wherein the solder tip ~~(21)~~ is arranged on a shaft ~~(22)~~, whereby the shaft is journalled in a bearing housing ~~(23)~~ which permits relative axial movement, wherein the depth into which the solder tip ~~(21)~~ is pressed down is determined by the total weight of the solder tip ~~(21)~~ and the shaft ~~(22)~~ and by the friction in the bearing housing ~~(23)~~.

8. (currently amended) ~~A~~ The method according to claim 6, ~~characterized in that~~ wherein the solder tip ~~(21)~~ is arranged on a shaft ~~(22)~~, whereby the shaft is journalled in a bearing housing ~~(23)~~ that permits relative axial movement, and that wherein the shaft ~~(21)~~ is provided with a compression spring ~~(27)~~, whereby the depth into which the solder tip ~~(21)~~ is pressed down is determined by the total weight of the solder tip ~~(21)~~, the shaft ~~(22)~~ and the compression spring ~~(27)~~, the friction in the bearing housing ~~(23)~~ plus the compression of the compression spring ~~(27)~~.

9. (currently amended) ~~A~~ The method according to ~~any of the preceding claims, characterized in that~~ claim 1, wherein the solder tip ~~(21)~~ is arranged on a shaft ~~(22)~~, whereby the solder tip ~~(21)~~ during the pre-soldering is brought to rotate in the direction of rotation of the shaft ~~(22)~~.

10. (currently amended) ~~A~~ The method according to claim 9, ~~characterized in that~~ wherein the solder tip ~~(21)~~ is brought to rotate in one or the other direction of rotation, or ~~that~~ wherein the rotation is reversing.

11. (currently amended) ~~A~~ The method according to claim 10, ~~characterized in that~~ wherein the rotation is less than one complete turn, that is, is less than 360°.

12. (currently amended) ~~A~~ The method according to ~~any of the preceding claims, characterized in that~~ claim 1, wherein the temperature of the solder in the solder pot is in the interval of between 300°C and 400 °C.

13. (currently amended) ~~A~~ The method according to ~~any of the preceding claims, characterized in that~~ claim 1, wherein the solder contains tin and zinc.

14. (currently amended) ~~A~~ The method according to claim 13, ~~characterized in that~~ wherein the solder contains 75% tin and 25% zinc.

15. (currently amended) Equipment ~~(10)~~ for carrying out the method according to ~~any of claims 1-14, characterized in that it comprises~~ claim 1, the equipment comprising:

a solder pot ~~(20)~~,

a solder head ~~(12), whereby the solder head is arranged with~~ comprising a first linear module ~~(13)~~ for movements in the x-direction (horizontally) and a second linear module ~~(14)~~ for

movements in the y-direction (vertically), ~~and~~

a press unit ~~(15)~~ for fixing the capacitor elements ~~(1)~~, and

a steel frame on which ~~wherein~~ the solder pot ~~(20)~~, the solder head ~~(12)~~, the first and second ~~(13, 14)~~ linear modules and the press unit ~~(15)~~ are arranged ~~on a steel frame (11)~~.

16. (currently amended) ~~Equipment~~ The equipment according to claim 15, ~~characterized in that~~ wherein the solder head ~~(12) is arranged with~~ comprises a solder tip ~~(21) provided with~~ including an active tip ~~(26)~~, said solder tip being arranged on a shaft ~~(22)~~ and a turning device ~~(25)~~, whereby the shaft ~~(22)~~ is connected to the turning device ~~(25)~~ with an insulating shaft ~~(24)~~ and whereby the shaft ~~(22)~~ is journalled in a bearing housing ~~(23)~~.

17. (currently amended) ~~Equipment~~ The equipment according to claim 16, ~~characterized in that~~ wherein the shaft ~~(22)~~ and the insulating shaft ~~(24)~~ are arranged so that a guide pin prevents relative axial movement.

18. (currently amended) ~~Equipment~~ The equipment according to claim 16, ~~characterized in that~~ wherein the shaft ~~(22)~~ and the insulating shaft ~~(24)~~ are arranged so that a guide pin, running in an axial slit, makes possible a relative axial movement.

19. (currently amended) ~~Equipment~~ The equipment according to claim 18, ~~characterized in that~~ wherein a compression spring ~~(27)~~ is arranged between the shaft ~~(22)~~ and the turning device ~~(25)~~, whereby the compression spring ~~(27)~~ counteracts the shaft ~~(22)~~ being moved in a direction towards the turning device ~~(25)~~.

20. (currently amended) ~~Equipment~~ The equipment according to ~~any of claims 16-19, characterized in that~~ claim 16, wherein the turning device ~~(25)~~ is arranged so that a rotating movement is transmitted to the solder tip ~~(21)~~.

21. (currently amended) ~~Equipment~~ The equipment according to ~~any of claims 16-20, characterized in that~~ claim 16, wherein the active tip ~~(26)~~ is arranged with a rotationally symmetrical cross section.

22. (currently amended) ~~Equipment~~ The equipment according to claim 21, ~~characterized in that~~ wherein the active tip ~~(26)~~ is arranged with a smooth end surface.

23. (currently amended) ~~Equipment~~ The equipment according to claim 21, ~~characterized in that~~ wherein the active tip ~~(26)~~ is arranged with an end surface with turned circular recesses.

24. (currently amended) ~~Equipment~~ The equipment according to claim 21, ~~characterized in that~~ wherein the active tip ~~(26)~~ is arranged with recesses so as to form a grid-like pattern on the end surface.

25. (currently amended) ~~Equipment~~ The equipment according to claim 21, ~~characterized in that~~ wherein the active tip ~~(26)~~ is arranged with a cupped end surface.

26. (currently amended) ~~Equipment~~ The equipment according to ~~any of claims 16-20,~~

~~characterized in that~~ claim 16, wherein the active tip ~~(26)~~ is arranged with a rectangular cross section.

27. (currently amended) ~~Equipment~~ The equipment according to ~~any of claims 15-26, characterized in that~~ claim 15, wherein the equipment ~~(10) is provided with~~ comprises a ~~Programmable Logic Controller (PLC)~~ programmable logic controller and a control panel for controlling the solder pot ~~(20)~~, the solder head ~~(12)~~, the first and second linear modules ~~(13, 14)~~, and the press unit ~~(15)~~.